



## **Datasheet**

## **Non-Eurocard Prototyping Board**

RS Stock number 159-6209



## **DIP Breadboard**

A range of low density boards for hard wiring of integrated circuits, particularly useful in R & D applications. OV and Vcc rail patterns are duplicated on the component side of the board giving increased power capacity. These boards do not have gold plated contacts, therefore offering a cost saving over plug-in boards.

In place of contacts, individual mounting pads for terminal pins are provided.

## **Features**

- · Ideal for hard wired applications
- Grid print to aid component layout
- Full range of terminal pins available for interfacing

Board dims	Rows/Pads	Rows/Pads	Base material
203,30 x 194,31	5/76	5/76	SRBP

Notes: 7,62 pitch IC DIP 15,24 pitch IC DIP; hole grid 2,54 x 2,54mm hole dia. 1,02mm